



Flexible PCB Capacity

Process capability for single layer, double layer and multilayer flexible circuits.

Technical Index

ITEM	TECHNICAL INDEX
Layer count	Single layer, double layer and multilayer
Base material	PI, FR4, PET
Base copper thickness	9, 12, 18, 35 and 70 μm
Maximum board size	406 x 610 mm (16 x 24 in)
Minimum hole, drilled	$\phi 0.1$ mm (0.004 in)
Minimum hole, punched	$\phi 0.5$ mm (0.02 in)
Plated hole tolerance	± 0.05 mm (± 0.002 in)
Minimum track width	0.05 mm (2 mil)
Minimum track gap	0.05 mm (2 mil)
Surface treatment	Plated or immersion tin, plated or immersion gold, OSP
Outline treatment	Precise V-cut, punch, milled, laser outline
Outline tolerance	± 0.05 mm
Coverlay	PI film and PET film lamination
Solder resist inks	LPI soldermask, UV-cured soldermask, legend ink, peelable soldermask, carbon ink, silver paste
Peeling strength	1.0 kgf/cm with adhesive copper, 0.5 kgf/cm with adhesiveless copper
Legend colours	Multiple silk-screen colours

Outline Processes

- **Precise V-cut** — straight break lines in an array.
- **Punching** — fast and repeatable for volume with a simple shape.
- **Milling** — one-off and low volume shapes.
- **Laser outline** — fine detail and tight internal radii.

All four are held to an outline tolerance of ± 0.05 mm.